

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 07-018438

(43)Date of publication of application : 20.01.1995

(51)Int.Cl.

C23C 14/50
B23Q 3/15
H01L 21/203
H01L 21/3065
H01L 21/68

(21)Application number : 05-146486

(71)Applicant : ANELVA CORP

(22)Date of filing : 17.06.1993

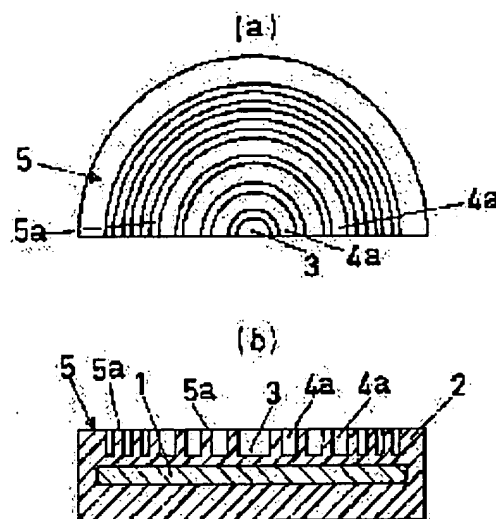
(72)Inventor : DOI HIROSHI

(54) ELECTROSTATIC CHUCK DEVICE

(57)Abstract:

PURPOSE: To provide an electrostatic chuck device capable of eliminating a temp. difference in a substrate to be treated with plasma.

CONSTITUTION: The substrate supporting face of a flat electrode 1 is covered with an insulating material 2, and a rugged face 5 is formed on the surface of the insulating material 2. The density of the recessed surface 5b, the density of the protrusion surface 5a or the depth of the recessed surface 5b in the formed rugged face 5 are changed in the surface of insulating material to distribute the electrostatic attraction to be exerted on the substrate. Reciprocity is established between the trend in the distribution of electrostatic attraction and that in the temp. distribution in the substrate by plasma treatment, and the temp. distribution is uniformized in the substrate.



LEGAL STATUS

[Date of request for examination] 08.06.2000

[Date of sending the examiner's decision of rejection] 11.03.2003

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office